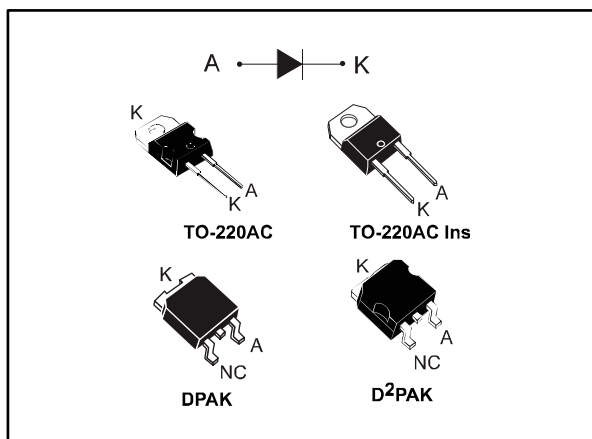


650 V power Schottky silicon carbide diode

Datasheet - production data



Description

The SiC diode is an ultra high performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, this ST SiC diode will boost performance in hard switching conditions. Its high forward surge capability ensures good robustness during transient phases.

Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Dedicated to PFC applications
- High forward surge capability
- Insulated package: TO-220AC Ins
- Insulated voltage: 2500 V_{RMS} sine
- Typical package capacitance: 7 pF

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	10 A
V_{RRM}	650 V
$T_j (max.)$	175 °C

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		650	V
$I_{F(RMS)}$	Forward rms current		22	A
$I_{F(AV)}$	Average forward current	TO-220AC, DPAK, D ² PAK, $T_c = 135\text{ °C}^{(1)}$, DC	10	A
		TO-220AC Ins, $T_c = 85\text{ °C}^{(1)}$, DC		
I_{FRM}	Repetitive peak forward current	TO-220AC, DPAK, D ² PAK, $T_c = 135\text{ °C}^{(1)}$, $T_j = 175\text{ °C}$, $\delta = 0.1$	41	A
		TO-220AC Ins, $T_c = 85\text{ °C}^{(1)}$, $T_j = 175\text{ °C}$, $\delta = 0.1$		
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal, $T_c = 25\text{ °C}$	90	A
		$t_p = 10\text{ ms}$ sinusoidal, $T_c = 125\text{ °C}$	80	
		$t_p = 10\text{ }\mu\text{s}$ square, $T_c = 25\text{ °C}$	470	
T_{stg}	Storage temperature range		-55 to +175	°C
T_j	Operating junction temperature ⁽²⁾		-40 to +175	°C

Notes:
⁽¹⁾Value based on $R_{th(j-c)}$ max.

⁽²⁾ $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal parameters

Symbol	Parameter		Value		Unit
			Typ.	Max.	
$R_{th(j-c)}$	Junction to case	TO-220AC, DPAK, D ² PAK	1.25	1.5	°C/W
		TO-220AC Ins	2.1	3.5	

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	9	100	μA
		$T_j = 150\text{ °C}$		-	85	425	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 10\text{ A}$	-	1.56	1.75	V
		$T_j = 150\text{ °C}$		-	1.98	2.5	

Notes:
⁽¹⁾Pulse test: $t_p = 10\text{ ms}$, $\delta < 2\%$
⁽²⁾Pulse test: $t_p = 500\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.35 \times I_{F(AV)} + 0.115 \times I_{F(RMS)}^2$$

Table 5: Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Typ.	Unit
$Q_{cj}^{(1)}$	Total capacitive charge	$V_R = 400 \text{ V}$	28.5	nC
C_j	Total capacitance	$V_R = 0 \text{ V}, T_c = 25 \text{ }^\circ\text{C}, F = 1 \text{ MHz}$	480	pF
		$V_R = 400 \text{ V}, T_c = 25 \text{ }^\circ\text{C}, F = 1 \text{ MHz}$	48	

Notes:

⁽¹⁾Most accurate value for the capacitive charge: $Q_{cj} = \int_0^{V_{OUT}} C_j(V_R) \cdot dV_R$

1.1 Characteristics (curves)

Figure 1: Forward voltage drop versus forward current (typical values, low level)

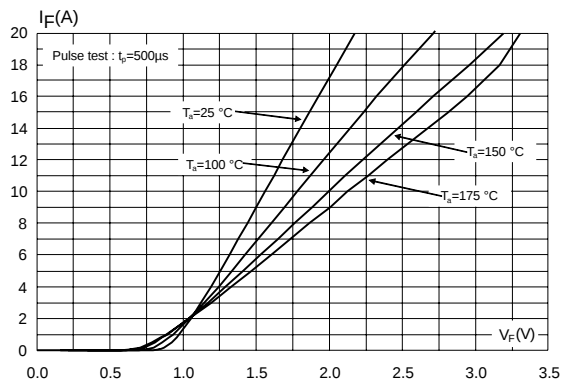


Figure 2: Forward voltage drop versus forward current (typical values, high level)

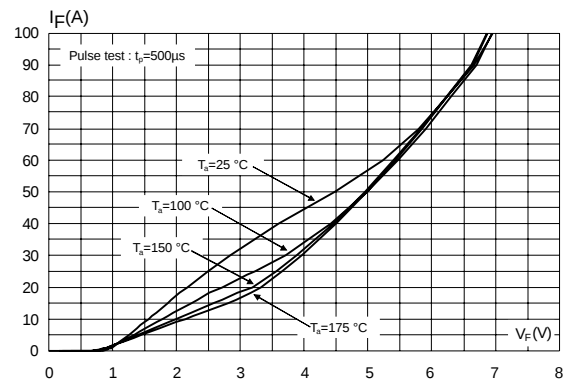


Figure 3: Reverse leakage current versus reverse voltage applied (typical values)

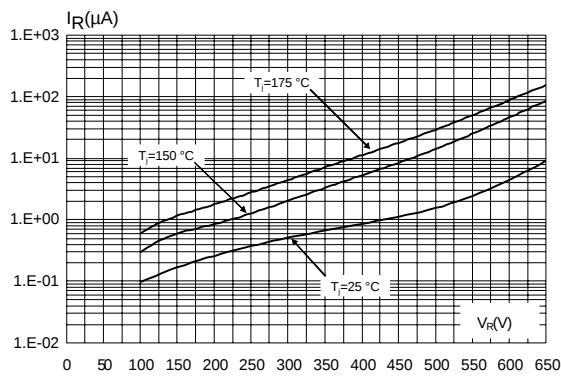


Figure 4: Peak forward current versus case temperature (TO-220AC, DPAK, D²PAK)

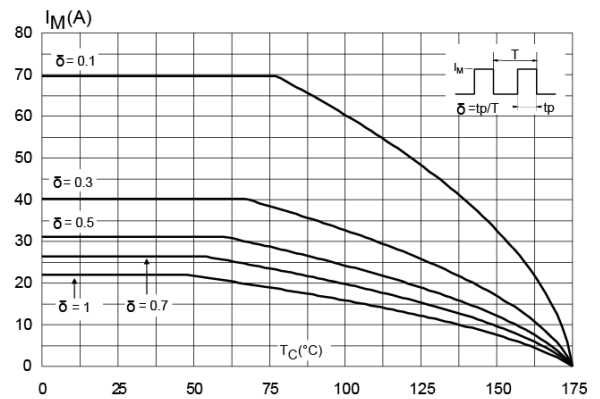


Figure 5: Peak forward current versus case temperature (TO-220AC Ins)

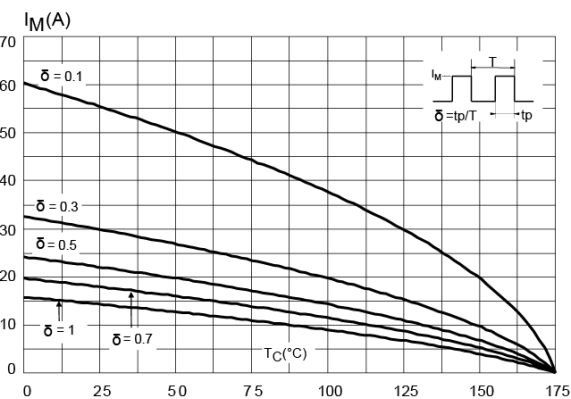


Figure 6: Junction capacitance versus reverse voltage applied (typical values)

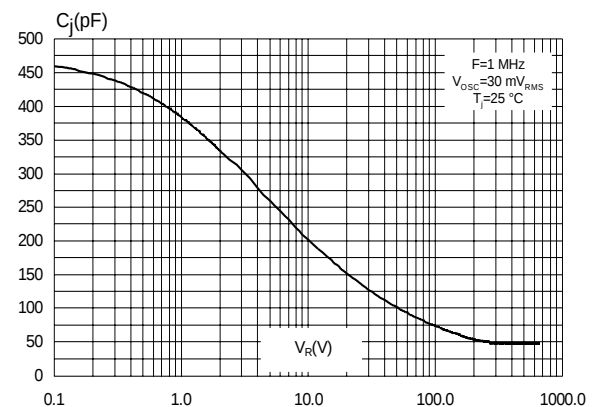


Figure 7: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC, DPAK and D²PAK)

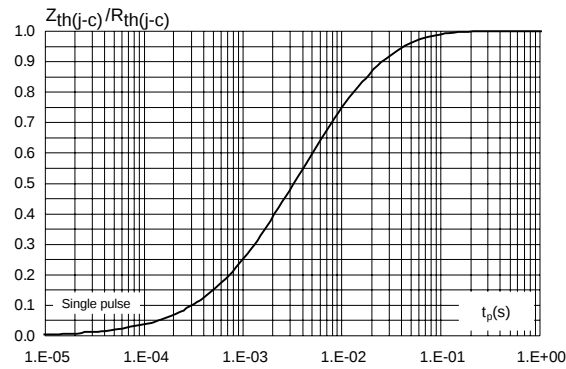


Figure 8: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC Ins)

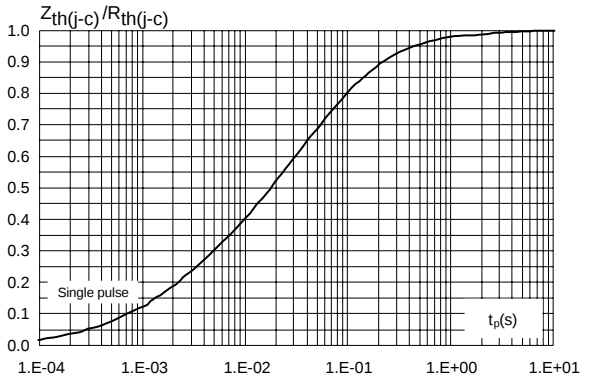


Figure 9: Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

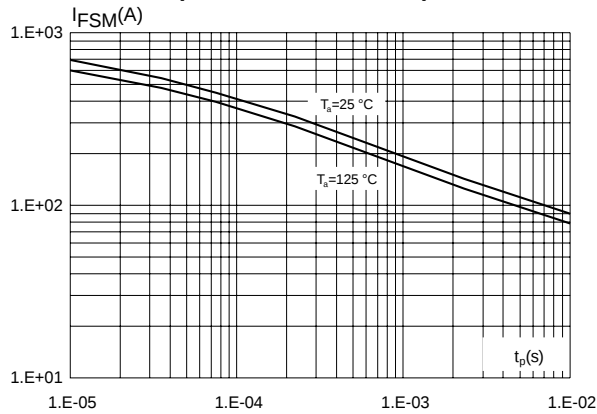


Figure 10: Total capacitive charges versus reverse voltage applied (typical values)

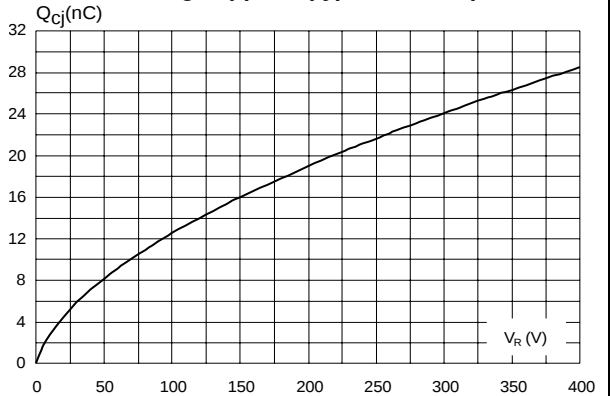
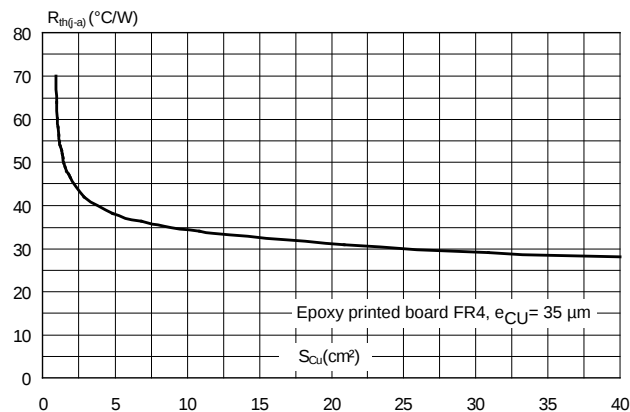


Figure 11: Thermal resistance junction to ambient versus copper surface under tab for D²PAK package (typical values)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.7 N·m

2.1 TO-220AC package information

Figure 12: TO-220AC package outline

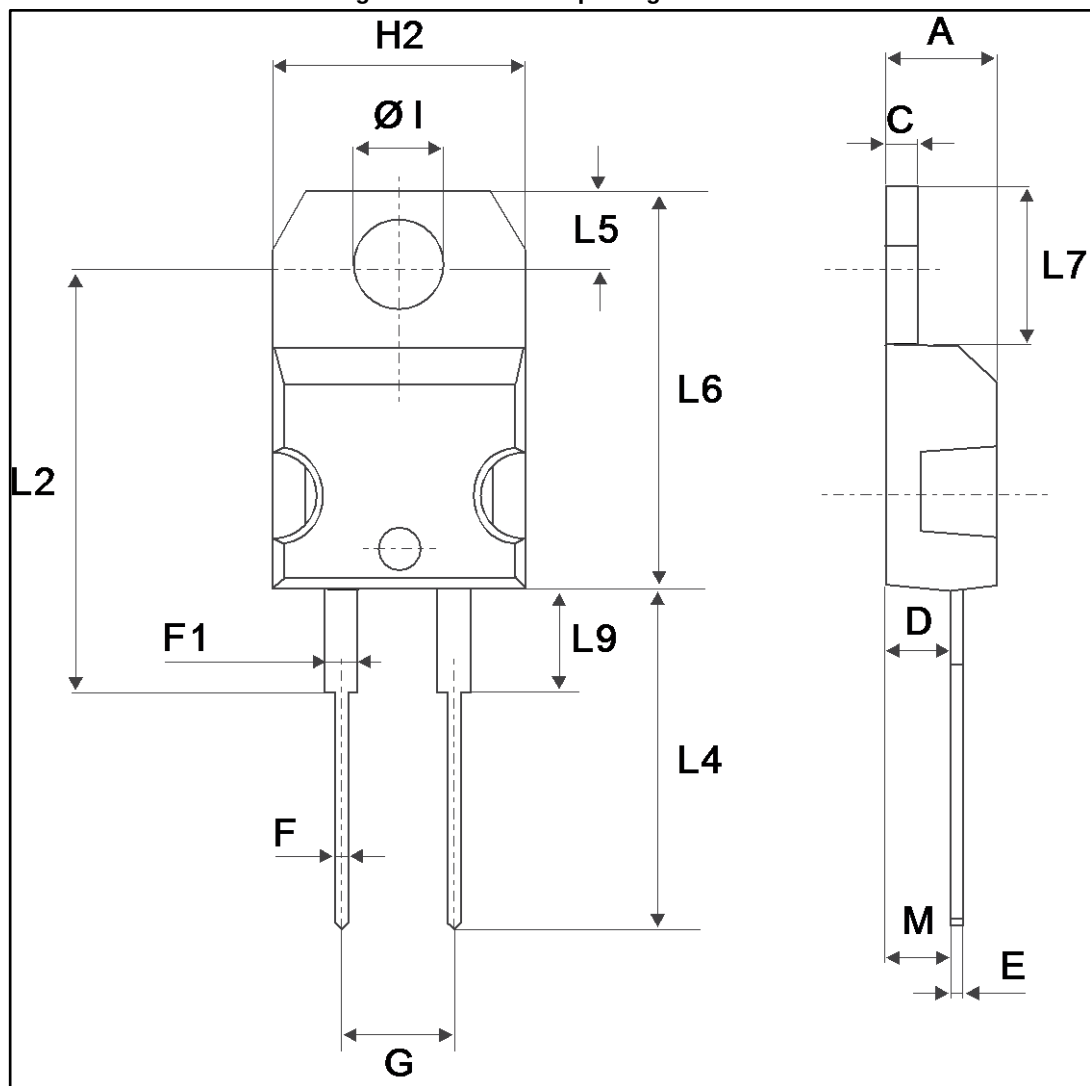


Table 6: TO-220AC package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam	3.75	3.85	0.147	0.151

2.2 TO-220AC Ins package information

Figure 13: TO-220AC Ins package outline

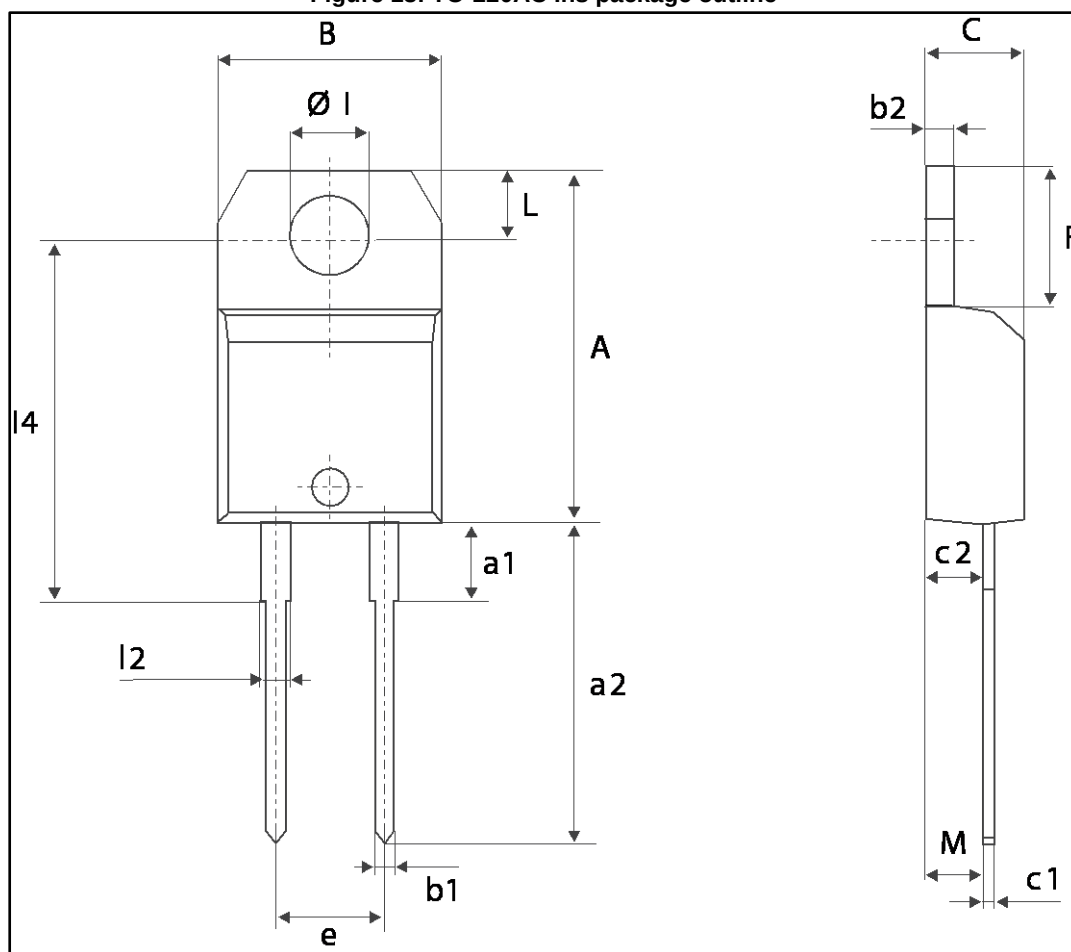
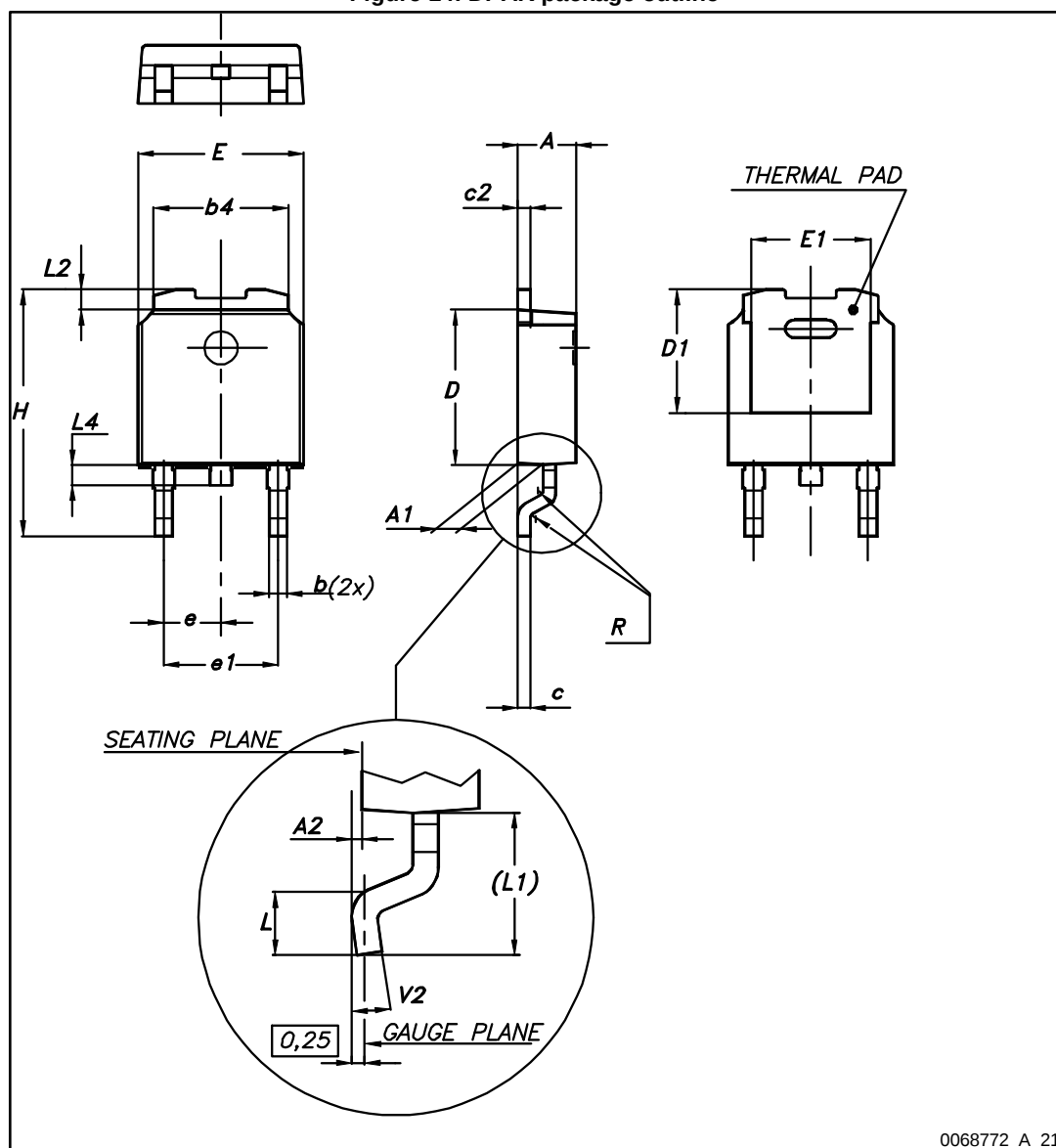


Table 7: TO-220AC Ins package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	15.20	15.90	0.598	0.625
a1	3.75 typ.		0.147 typ.	
a2	13.00	14.00	0.511	0.551
B	10.00	10.40	0.393	0.409
b1	0.61	0.88	0.024	0.034
b2	1.23	1.32	0.048	0.051
C	4.40	4.60	0.173	0.181
c1	0.49	0.70	0.019	0.027
c2	2.40	2.72	0.094	0.107
e	4.80	5.40	0.189	0.212
F	6.20	6.60	0.244	0.259
ØI	3.75	3.85	0.147	0.151

2.3 DPAK package information

Figure 14: DPAK package outline

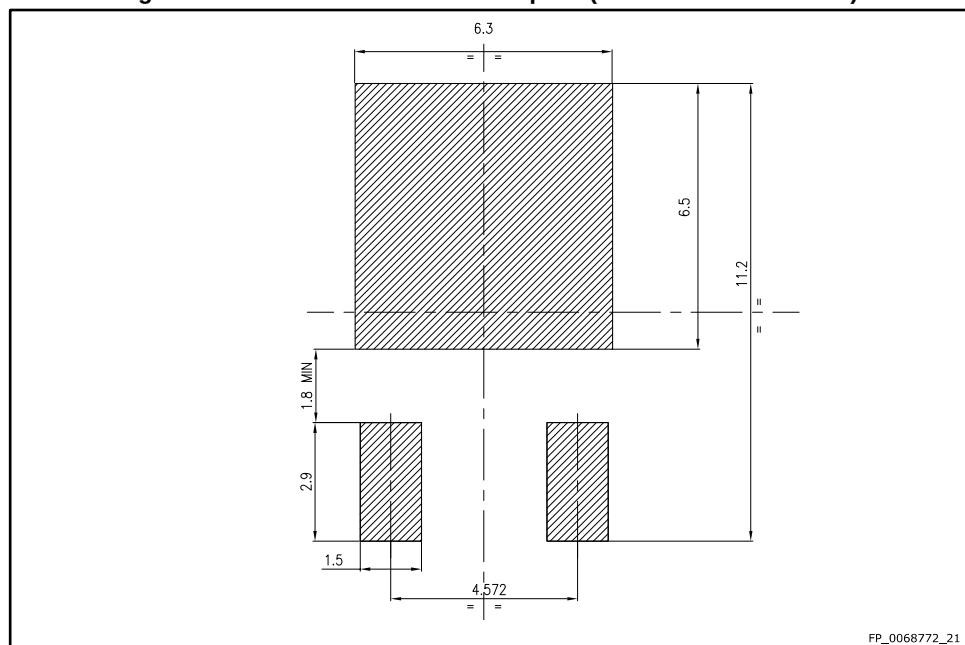


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Table 8: DPAK mechanical data

Dim.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
b	0.64		0.90	0.025		0.035
b4	5.20		5.40	0.205		0.213
c	0.45		0.60	0.018		0.024
c2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
D1	4.95	5.10	5.25	0.201	0.195	0.207
E	6.40		6.60	0.252		0.260
E1	4.60	4.70	4.80	0.181	0.185	0.189
e	2.16	2.28	2.40	0.085	0.090	0.094
e1	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L	1.00		1.50	0.039		0.059
(L1)	2.60	2.80	3.00	0.102	0.110	0.118
L2	0.65	0.80	0.95	0.026	0.031	0.037
L4	0.60		1.00	0.024		0.039
R		0.20			0.008	
V2	0°		8°	0°		8°

Figure 15: DPAK recommended footprint (dimensions are in mm)



2.4 D²PAK package information

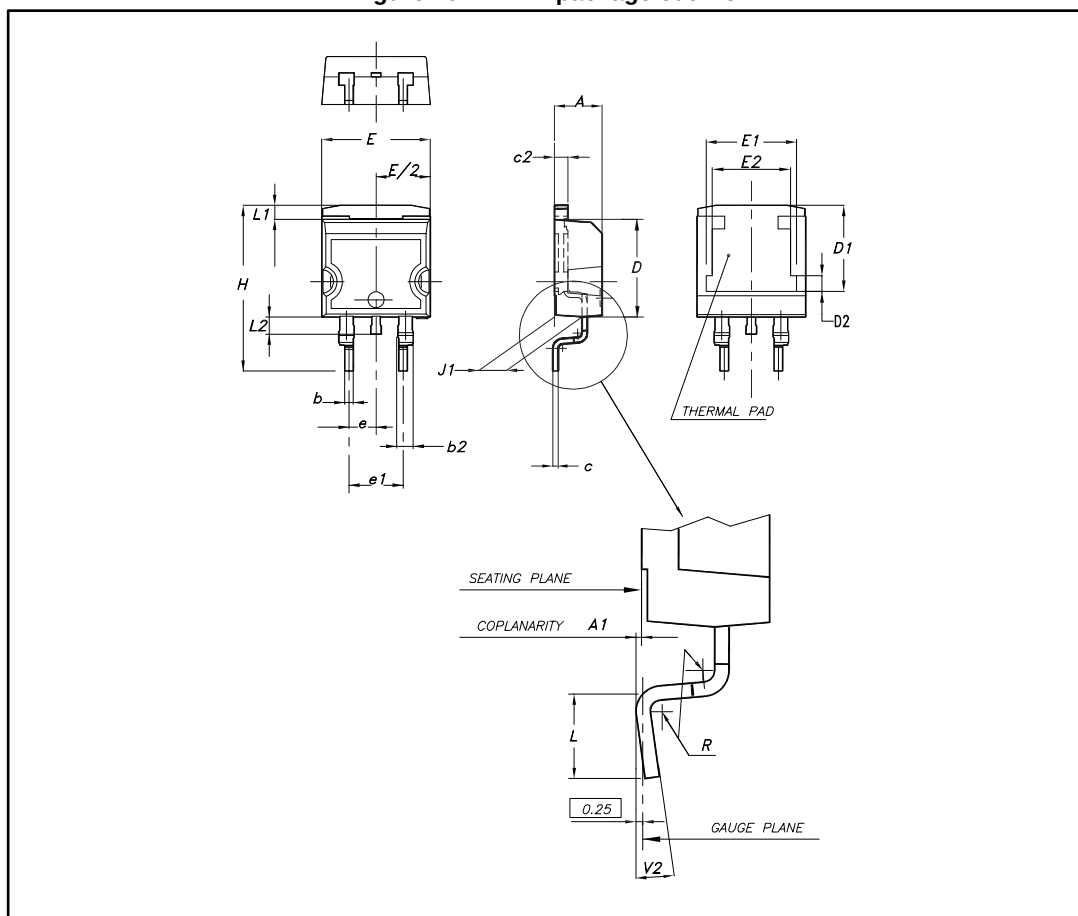
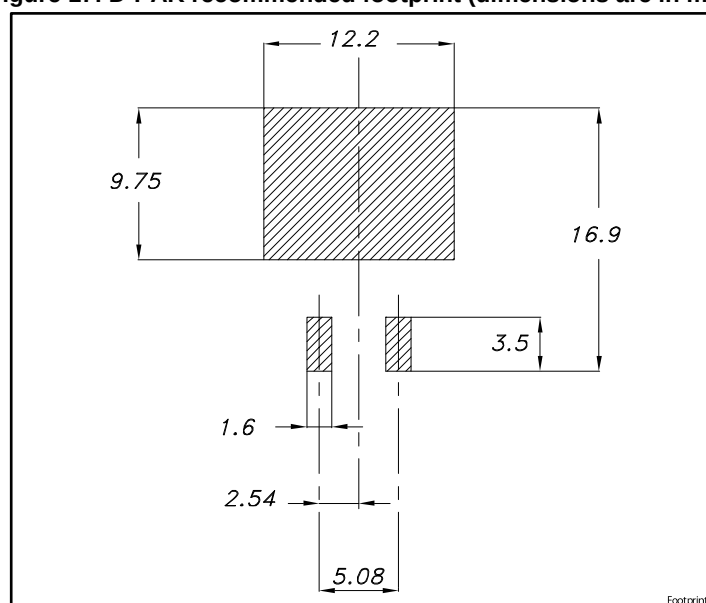
Figure 16: D²PAK package outline

Table 9: D²PAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.028		0.037
b2	1.14		1.70	0.045		0.067
c	0.45		0.60	0.018		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50	7.75	8.00	0.295	0.305	0.315
D2	1.10	1.30	1.50	0.043	0.051	0.060
E	10		10.40	0.394		0.409
E1	8.50	8.70	8.90	0.335	0.343	0.346
E2	6.85	7.05	7.25	0.266	0.278	0.282
e		2.54			0.100	
e1	4.88		5.28	0.190		0.205
H	15		15.85	0.591		0.624
J1	2.49		2.69	0.097		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.049		0.055
L2	1.30		1.75	0.050		0.069
R		0.4			0.015	
V2	0°		8°	0°		8°

Figure 17: D²PAK recommended footprint (dimensions are in mm)

3 Ordering information

Table 10: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPSC10H065G-TR	STPSC10H065G	D ² PAK	1.48 g	1000	Tape and reel
STPSC10H065D	STPSC10H065D	TO-220AC	1.86 g	50	Tube
STPSC10H065DI	STPSC 10H065DI	TO-220AC Ins	2.12 g	50	Tube
STPSC10H065B-TR	PSC10 H065	DPAK	0.32 g	2500	Tape and reel

4 Revision history

Table 11: Document revision history

Date	Revision	Changes
31-Aug-2012	1	First issue.
10-Oct-2012	2	Added Max. value to Table 3.
07-Nov-2013	3	Updated Figure 1, Figure 2, Figure 13, Figure 14 and Table 8.
07-Jan-2014	4	Added TO-220AC Ins package.
22-Jul-2015	5	Updated Table 10 and reformatted to current standard.
10-Dec-2015	6	Inserted package name on cover page.
06-Feb-2017	7	Updated D ² PAK package section.

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